

Features

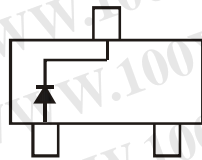
- Low Turn-on Voltage
- Fast Switching
- PN Junction Guard Ring for Transient and ESD Protection
- **Lead Free/RoHS Compliant (Note 1)**
- **“Green” Molding Compound (No Br, Sb) (Note 2)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

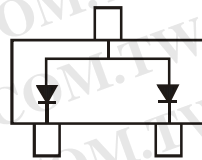
- Case: SOT23
- Case Material: Molded Plastic, “Green” Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Polarity: See Diagrams Below
- Weight: 0.008 grams (approximate)



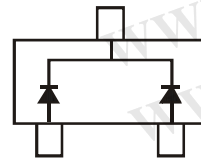
Top View



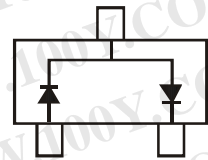
BAT54



BAT54A



BAT54C



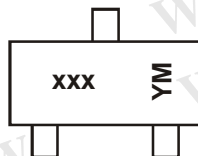
BAT54S

Ordering Information (Note 3)

Part Number	Qualification	Case	Packaging
BAT54-7-F	Commercial	SOT23	3000/Tape & Reel
BAT54A-7-F	Commercial	SOT23	3000/Tape & Reel
BAT54C-7-F	Commercial	SOT23	3000/Tape & Reel
BAT54S-7-F	Commercial	SOT23	3000/Tape & Reel
BAT54Q-7-F	Automotive	SOT23	3000/Tape & Reel
BAT54AQ-7-F	Automotive	SOT23	3000/Tape & Reel
BAT54CQ-7-F	Automotive	SOT23	3000/Tape & Reel
BAT54SQ-7-F	Automotive	SOT23	3000/Tape & Reel

- Notes:
1. No purposefully added lead.
 2. Products manufactured with date code VD (Week 50, 2008) and newer are built with Green Molding Compound. Products manufactured with date code prior to VD are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants.
 3. For packaging details, go to our website at <http://www.diodes.com>.

勝特力材料 886-3-5753170
勝特力电子(上海) 86-21-34970699
勝特力电子(深圳) 86-755-83298787
[Http://www.100y.com.tw](http://www.100y.com.tw)

Marking Information


- xxx = Product Type Marking Code
 KL1 = BAT54
 KL2 = BAT54A
 KL3 = BAT54C
 KL4 = BAT54S
 YM = Date Code Marking
 Y = Year (ex: T = 2006)
 M = Month (ex: 9 = September)

Date Code Key

Year	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	J	K	L	M	N	P	R	S	T	U	V	W	X	Y	Z	A	B	C
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec						
Code	1	2	3	4	5	6	7	8	9	O	N	D						

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	30	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
Forward Continuous Current (Note 4)	I _F	200	mA
Repetitive Peak Forward Current	I _{FRM}	300	mA
Forward Surge Current @ t < 1.0s	I _{FSM}	600	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4)	P _D	200	mW
Thermal Resistance, Junction to Ambient Air (Note 4)	R _{θJA}	500	°C/W
Operating and Storage Temperature Range (Note 5)	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V _{(BR)R}	30	—	—	V	I _{RS} = 100μA
Forward Voltage	V _F	—	—	240 320 400 500 800	mV	I _F = 0.1mA I _F = 1mA I _F = 10mA I _F = 30mA I _F = 100mA
Reverse Leakage Current (Note 6)	I _R	—	—	2.0	μA	V _R = 25V
Total Capacitance	C _T	—	—	10	pF	V _R = 1.0V, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	—	5.0	ns	I _F = 10mA through I _R = 10mA to I _R = 1.0mA, R _L = 100Ω

Notes: 4. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at <http://www.diodes.com>.
 5. The heat generated must be less than the thermal conductivity from Junction-to-Ambient: dP_D/dT_J < 1/R_{θJA}
 6. Short duration test pulse used to minimize self-heating effect.

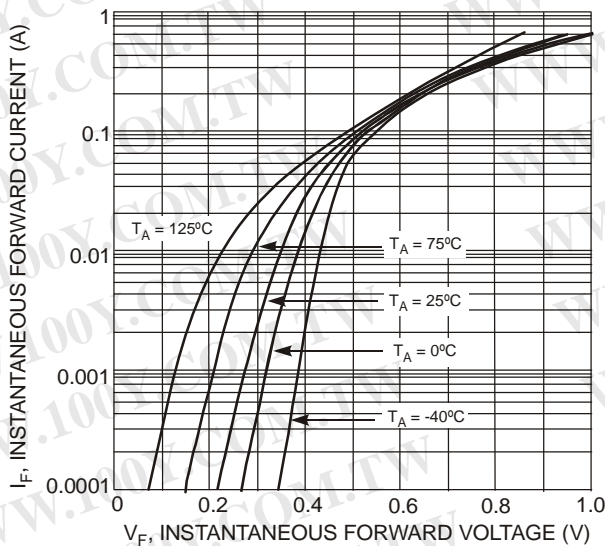


Fig. 1 Typical Forward Characteristics

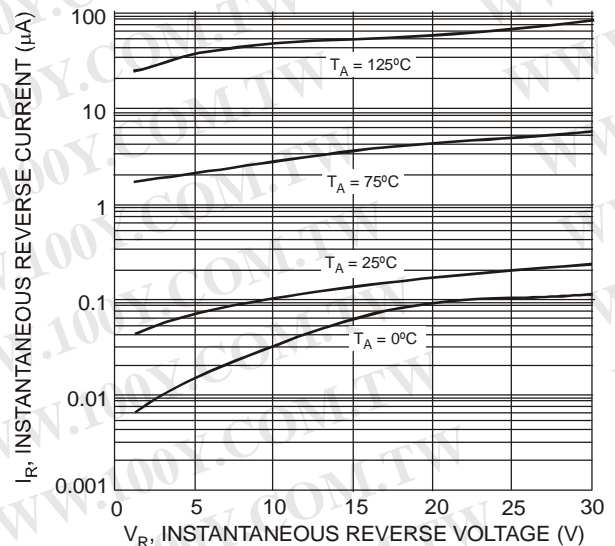


Fig. 2 Typical Reverse Characteristics

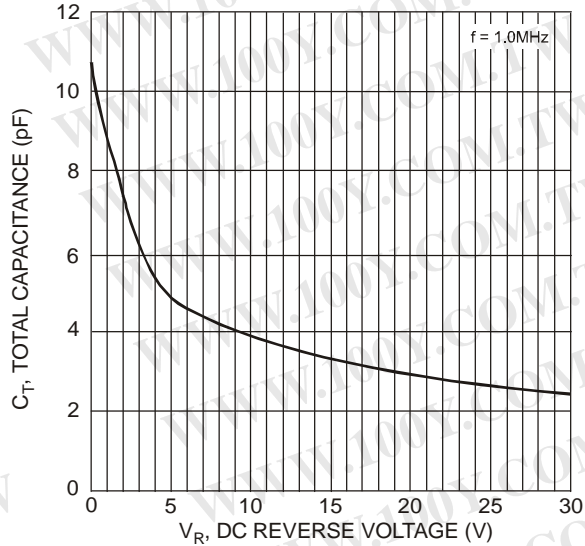


Fig. 3 Total Capacitance vs. Reverse Voltage

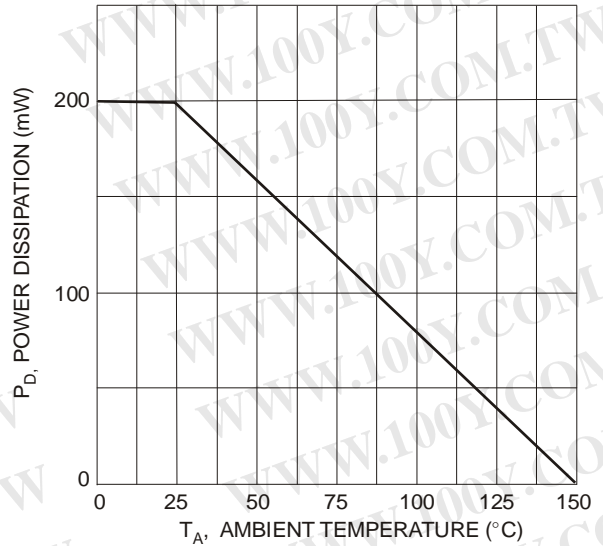
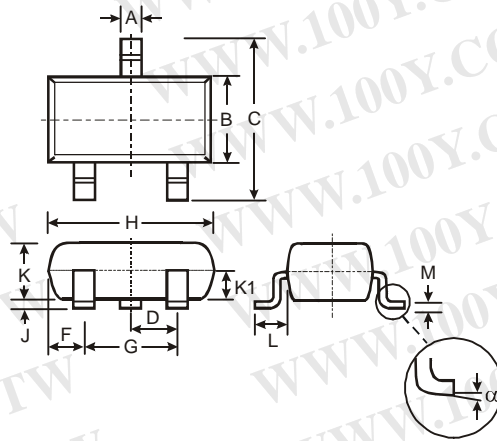


Fig. 4 Power Derating Curve

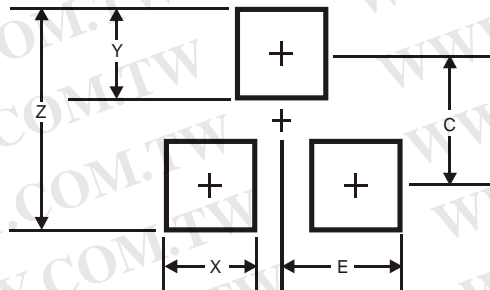
Package Outline Dimensions



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.903	1.10	1.00
K1	-	-	0.400
L	0.45	0.61	0.55
M	0.085	0.18	0.11
α	0°	8°	-

All Dimensions in mm

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

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